


APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-40 °C TO +85 °C(NOTE1) 	STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE2)	
	OPERATING HUMIDITY RANGE	40 % TO 80 %(NOTE3)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE2)	
	VOLTAGE	AC 250 V	UL · CSA VOLTAGE	AC 30V	
	CURRENT	2A	RATING CURRENT	2A	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
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CONSTRUCTION

GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.		x	x

ELECTRIC CHARACTERISTICS


CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	x	—
INSULATION RESISTANCE	500 V DC.	1000 MΩ MIN.	x	—
VOLTAGE PROOF	650 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	x	—

MECHANICAL CHARACTERISTICS

MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—



ENVIRONMENTAL CHARACTERISTICS

DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 TO 95 %, 96 h.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 →5 TO 35→85 →5 TO 35 °C TIME 30 →10 TO 15→10→15 TO 3 min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
RESISTANCE TO SOLDERING HEAT	1)AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE : 260°C FOR IMMERSION, DURATION , 10 sec . 2)MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300°C SOLDERING TIME : 2 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	x	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230°C FOR IMMERSION DURATION, 3 sec.	SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMERSED	x	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-H-008540	MI. SAKIMURA	HK. UMEHARA	14. 02. 26

REMARKS NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD. AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. NOTE3:NON-CONDENSING. Unless otherwise specified, refer to IEC 60512.	APPROVED	KJ. KATAYOSE	05. 01. 05
	CHECKED	TY. OMA	05. 01. 05
	DESIGNED	IO. DENPOUYA	05. 01. 05
	DRAWN	IO. DENPOUYA	05. 01. 05

Note QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.	ELC4-080551-01
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	SPECIFICATION SHEET	PART NO.	DF11-*DP-2DSA (01)		
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL543		1/1